#### MICROWAVE POWER GaAs FET

## Internally Matched Power GaAs FETs (C-Band)

#### **Features**

- · High power
  - $P_{1dB}$  = 36.0 dBm at 4.9 GHz to 5.1 GHz
- · High gain
- G<sub>1dB</sub> = 10.0 dB at 4.9 GHz to 5.10 GHz
   Broad band internally matched
- · Hermetically sealed package

#### RF Performance Specifications ( $T_a = 25^{\circ}$ C)

Characteristics	Symbol	Condition	Unit	Min.	Тур.	Max
Output Power at 1dB Compression Point	P <sub>1dB</sub>		dBm	35.0	36.0	_
Power Gain at 1dB Compression Point	G <sub>1dB</sub>	V <sub>DS</sub> = 10V f = 4.9 ~ 5.1 GHz	dB	9.0	10.0	_
Drain Current	I <sub>DS</sub>		А	_	1.1	1.5
Power Added Efficiency	η <sub>add</sub>		%	_	33	_
Channel-Temperature Rise	$\Delta T_{ch}$	V <sub>DS</sub> xI <sub>DS</sub> xR <sub>th</sub> (c-c)	°C	_	-	80

### Electrical Characteristics (T<sub>a</sub> = 25° C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max
Trans-conductance	gm	$V_{DS} = 3V$ $I_{DS} = 1.5A$	mS	_	900	_
Pinch-off Voltage	V <sub>GSoff</sub>	$V_{DS} = 3V$ $I_{DS} = 20mA$	V	-2	-3.5	-5
Saturated Drain Current	I <sub>DSS</sub>	$V_{DS} = 3V$ $V_{GS} = 0V$	А	_	2.9	3.8
Gate to Source Breakdown Voltage	V <sub>GSO</sub>	I <sub>GS</sub> = -60 μA	V	-5	_	_
Thermal Resistance	R <sub>th (c-c)</sub>	Channel to case	°C/W	_	4.0	6.0

The information contained here is subject to change without notice.

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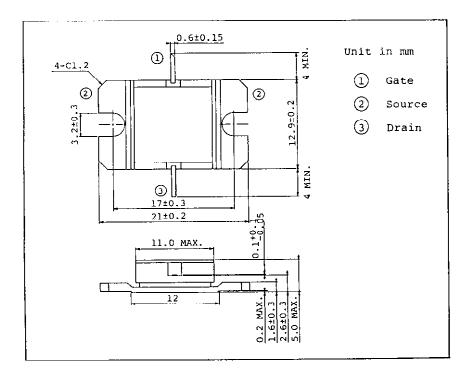
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# Absolute Maximum Ratings ( $T_a = 25^{\circ} C$ )

Characteristic	Symbol	Unit	Rating
Drain Source Voltage	V <sub>DS</sub>	V	15
Gate Source Voltage	V <sub>GS</sub>	V	-5
Drain Current	I <sub>D</sub>	А	4
Total Power Dissipation (Tc = 25°C)	P <sub>T</sub>	W	20
Channel Temperature	T <sub>ch</sub>	°C	175
Storage Temperature	T <sub>stg</sub>	°C	-65~175

#### Package Outline (2-11D1B)

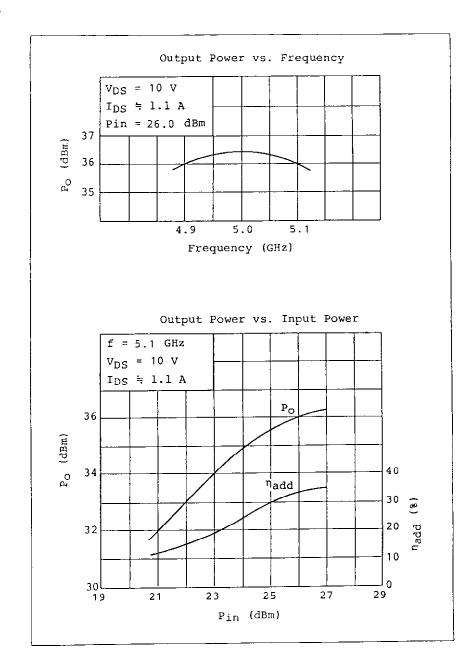


## **Handling Precautions for Packaged Type**

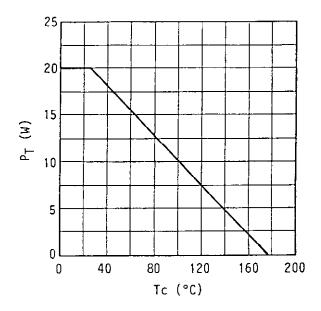
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

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#### **RF Performances**



# **Power Dissipation vs. Case Temperature**



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# TIM4951-4 S-Parameters (MAGN. and ANGLES)

 $V_{DS}$  = 10 V,  $I_{DS}$  = 1.0 A

